



Product Information Sheet

EPO-TEK® 354-T

Date:	September 2017	Recommended Cure: 150°C / 1 Hour
Rev:	III	
No. of Components:	Two	Minimum Alternative Cure(s):
Mix Ratio by Weight:	10 : 1	<i>May not achieve performance properties listed below</i>
Specific Gravity:	Part A: 1.12 Part B: 1.15	150°C / 10 Minutes
Pot Life:	3 Days	120°C / 30 Minutes
Shelf Life- Bulk:	Six months at room temperature	80°C / 2 Hours

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A two component, thixotropic, high Tg epoxy designed for semiconductor packaging in medical, fiber optic and optoelectronic assemblies. It is an electrically and thermally insulating epoxy and a more thixotropic version of EPO-TEK® 354.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
 Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Tan	Part B: Amber	
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 20 rpm:	11,000-20,000	cPs	
Thixotropic Index:	3.3		
* Glass Transition Temp:	≥ 95 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	51 x 10 ⁻⁶ in/in°C	
	Above Tg:	179 x 10 ⁻⁶ in/in°C	
Shore D Hardness:	85		
Lap Shear @ 23°C:	> 2,000 psi		
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	485 °C		
Weight Loss:			
	@ 200°C:	0.10 %	
	@ 250°C:	0.23 %	
	@ 300°C:	0.48 %	
Suggested Operating Temperature:	< 350 °C (Intermittent)		
Storage Modulus:	496,089 psi		
Ion Content:	Cl ⁻ :	38 ppm	Na ⁺ : 23 ppm
	NH ₄ ⁺ :	62 ppm	K ⁺ : 3 ppm
* Particle Size:	≤ 20 microns		

ELECTRICAL AND THERMAL PROPERTIES:	
Thermal Conductivity:	N/A
Volume Resistivity @ 23°C:	≥ 1 x 10 ¹³ Ohm-cm
Dielectric Constant (1KHz):	3.46
Dissipation Factor (1KHz):	0.008

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.